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Class 4, Wide Input Range, 15-W Power over Ethernet (PoE) Converter Reference Design



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Design Resources

PMP6659	Tool Folder Containing Design Files
TPS23756	Product Folder
TL431	Product Folder

Design Features

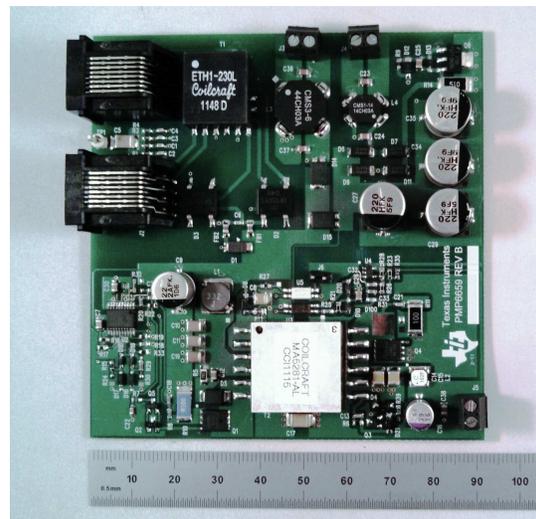
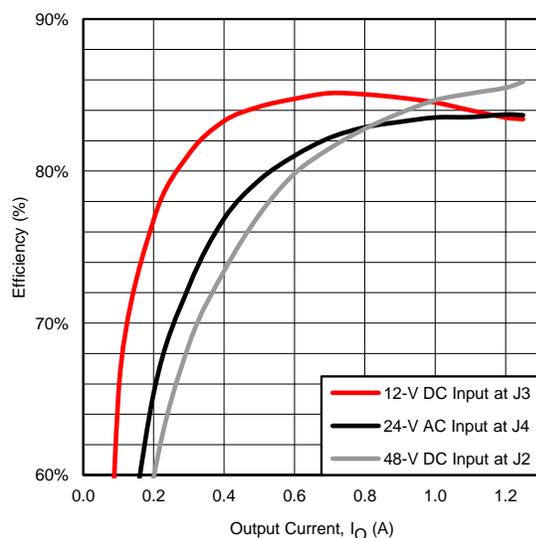
- Input voltage range: 10.8 to 57 VDC, 18 to 32VAC, or Power over Ethernet (PoE)
- 12-V at 1.25-A output
- Isolated flyback with synchronous rectifier for high efficiency
- Uses the TPS23756 high-power PoE interface and DC-DC controller
- Supports hardware Class 4 from the IEEE 802.3at standard

Featured Applications

- PoE Security Cameras
- Wireless LAN—Wireless Access Points



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1 System Description

The Class 4—Wide Input Range, 15-W Power over Ethernet (PoE) Converter reference design is intended for users to develop end-products for various internet protocol (IP) industrial applications. The reference design provides a complete guide for the hardware design of a flyback converter with synchronous rectification used for Class 4 PoE applications where a wide input range is required. The design files include schematics, Bill of Materials (BOMs), layer plots, Altium files, Gerber Files, and Fabrication Files.

This reference design has an optimized wide input voltage range. The output power is 12-V at 1.25-A (15-W) from either an adapter input (10.8 to 57 VDC or 18 to 32 VAC) or PoE. The synchronous rectifier provides excellent efficiency with the wide input voltage range. The wide input voltage range and high efficiency makes this design compatible with legacy applications where 12-VDC, 24-VDC, or 24-VAC auxiliary power is used. This design gives customers a ready-to-use high efficiency, wide input power design for building automation applications. The input and output combination of the design is typically required for PoE security cameras.

The core of this reference design is the PoE interface and DC-DC controller from TI, the TPS23756 device, that interfaces with the AC or DC-adapter input or the PoE input. The TPS23756 device is compliant with the IEEE 802.3at Power over Ethernet standard.

1.1 TPS23756

The TPS23756 device has a combined power-over-ethernet (PoE) powered-device (PD) interface and current-mode DC-DC controller optimized specifically for isolated converters. The PoE interface supports the IEEE 802.3at standard.

The TPS23756 device supports a number of input voltage ORing options including highest voltage, external adapter preference, and PoE preference. These features allow the designer to determine which power source will carry the load under all conditions.

The PoE interface features the new extended hardware classification necessary for compatibility with high-power midspan power sourcing equipment (PSE) per IEEE 802.3at. The detection signature pin can also be used to force power from the PoE source off. Classification can be programmed to any of the defined types with a single resistor.

The DC-DC controller features two complementary gate drivers with programmable dead time. This simplifies the design of active-clamp forward converters or optimized gate drive for highly-efficient flyback topologies. The second gate driver may be disabled if desired for single MOSFET topologies. The controller also features internal softstart, bootstrap startup source, current-mode compensation, and a 78% maximum duty cycle. A programmable and synchronizable oscillator allows design optimization for efficiency and eases use of the controller to upgrade existing power supply designs. Accurate programmable blanking, with a default period, simplifies the usual current-sense filter design trade-offs.

1.2 TL431

The TL431 is a three-terminal adjustable shunt regulator with specified thermal stability over applicable automotive, commercial, and military temperature ranges. The output voltage can be set to any value between V_{ref} (approximately 2.5 V) and 36 V, with two external resistors. These devices have a typical output impedance of 0.2 Ω . Active output circuitry provides a very sharp turn-on characteristic, making these devices excellent replacements for Zener diodes in many applications, such as onboard regulation, adjustable power supplies, and switching power supplies.

2 Design Features

- Input voltage range of 10.8 to 57 VDC, 18 to 32 VAC, or Power over Ethernet (PoE)
- 12-V at 1.25-A output
- Isolated flyback with synchronous rectifier for high efficiency
- Uses the TPS23756 high-power PoE interface and DC-DC controller
- Supports hardware Class 4 from the IEEE 802.3at standard

3 Block Diagram

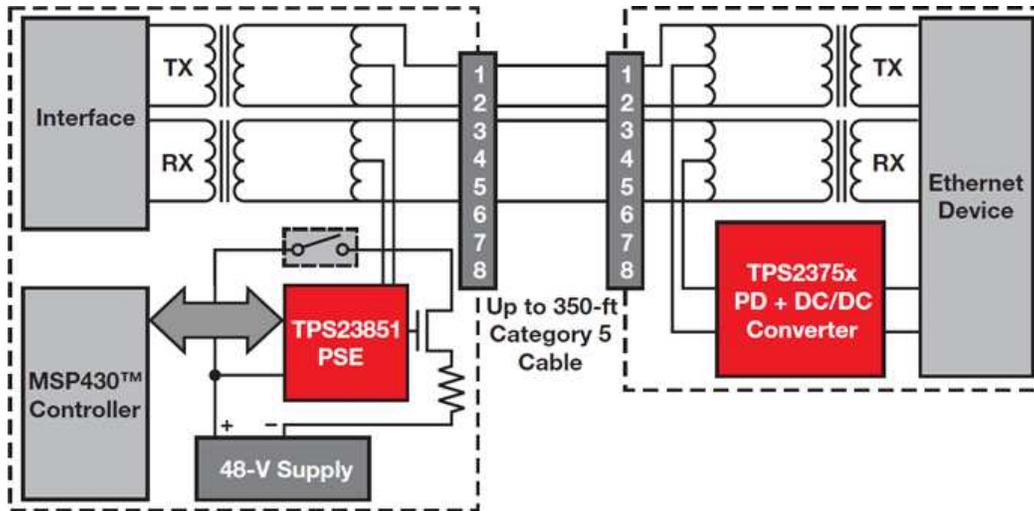


Figure 1. Block Diagram

4 Highlighted Products

The wide input range PoE converter reference design features the following devices:

- TPS23756
 - This device is a high-power and high-efficiency PoE interface and DC-DC controller.
- TL431
 - This device is an adjustable precision shunt-regulator.

For more information on each of these devices, see the respective product folders at www.TI.com.

4.1 TPS23756

- Powers up to 30-W (Input) PDs
- DC-DC control optimized for isolated converters
- Supports high-efficiency topologies
- Complete PoE interface
- Enhanced classification per IEEE 802.3at with status flag
- Adapter ORing support
- Programmable frequency with synchronization
- Robust 100-V, 0.5- Ω hotswap mOSFET
- -40°C to 125°C junction temperature range
- Industry standard PowerPAD™ TSSOP-20

4.2 TL431

- Equivalent full-range temperature coefficient, 30 ppm/ $^{\circ}\text{C}$
- 0.2- Ω typical output impedance
- Sink-current capability, 1 mA to 100 mA
- Low output noise
- Adjustable Output Voltage, V_{ref} to 36 V
- Available in a wide range of high-density packages

5 System Design Theory

5.1 PoE Hardware Classification

The reference design powered device (PD) supports hardware Class 4 from the IEEE 802.3at standard. This hardware classification allows PSE to determine the power requirements of a PDF before powering. This classification also helps with power management once power is applied. A Type 2 hardware classification permits high power PSEs and PDs to determine whether the connected device can support high-power operation. A Type 2 PD presents Class 4 in hardware to indicate that the PD is a high-power device. A Type 1 PSE recognizes a Class 4 device as a Class 0 device which allows for 13 W if the PSE chooses to power the PD.

The maximum power entries in [Table 1](#) determine the class classified by the PD. A Type 1 PD is not classified as Class 4. The PSE can disconnect a PD if the PD draws more than the power of the stated class, which is either the hardware class or a lower DLL-derived power level. The standard dictates that the PD draws limited-current peaks that increase the instantaneous power above the limited-current peaks listed in [Table 1](#). However, the average power requirement always applies to the PD.

Table 1. Power⁽¹⁾⁽²⁾

CLASS	CLASS REQUIREMENT		POWER AT PD		USAGE
	MIN (mA)	MAX (mA)	MIN (W)	MAX (W)	
0	0	4	0.44	12.95	Default
1	9	12	0.44	3.84	Optional
2	17	20	3.84	6.49	Optional
3	26	30	6.49	13	Optional
4	36	44	12.95	25.5	Only IEEE 802.3 at (Type 2) devices ⁽³⁾

⁽¹⁾ For a more detailed PoE overview with the TPS23756 device, please refer to the PoE Overview Section in the TPS23756 datasheet ([SLVS885](#)).

⁽²⁾ The yellow row indicates the PD classification for the PMP6659.

⁽³⁾ The IEEE 802.3at standard is an update to IEEE 802.3-2008 clause 33 (PoE), adding high-power options and enhanced classification. Standards change and should always be referenced when making design decisions.

5.2 Wide Input Range

This reference design supports a wide input range of 10.8 to 57 VDC, 18 to 32 VAC, or Power over Ethernet. The wide input voltage range makes this design compatible with legacy applications where 12-VDC, 24-VDC, or 24-VAC auxiliary power is used. When operating from an adaptor the TPS23756 device has a lower internal PoE undervoltage-lockout (UVLO) circuit allowing it to work with wider inputs. The IEEE 802.3at standard states that the nominal operating conditions from the PSE is 48-VDC but may vary between 42.5 to 57 VDC with a maximum-generated current rating typically at 600-mA per mode to protect the Ethernet cable from overheating. The DC-DC converter, after the PoE interface, converts the input to the applications operating voltage defined for this reference design as 12 V with a 1.25-mA load.

5.3 Other Recommended Devices

This reference design addresses legacy applications where 12-VDC, 24-VDC, or 24-VAC auxiliary power is used. Applications requiring an optimized PD and DC-DC Controller solution with high efficiency and does not require a wide input range should use the [TPS23751](#) device or the [TPS23752](#) device. Both devices have an evaluation module, [TPS23751EVM-104](#) and [TPS23752EVM-145](#), which is used to evaluate the performance of the TPS23751/2 IEEE 802.3at PoE Interface and Green-mode DC-DC Controller. See [Figure 2](#) for the TPS23751 and TPS23752 device light load efficiency versus mode.

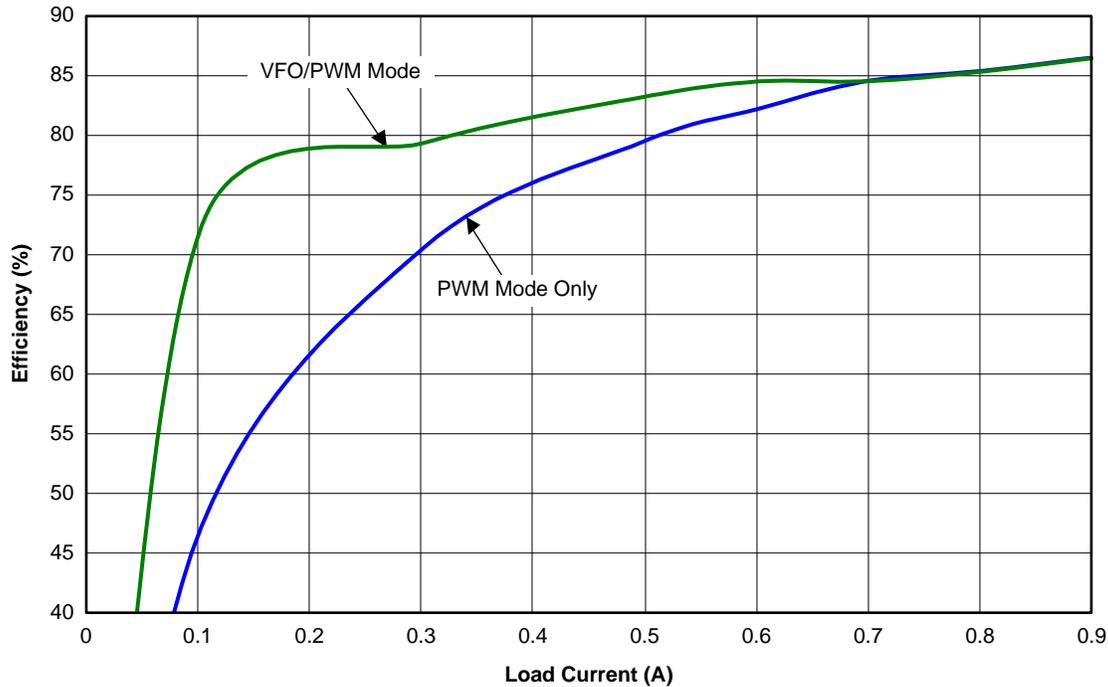


Figure 2. TPS23751 and TPS23752 Light Load Efficiency Versus Mode

5.4 Additional Application Notes

Description	TI Literature Number
Practical Guidelines to Designing an EMI Compliant PoE Powered Device with Isolated Flyback	SLUA469
Practical Guidelines to Designing an EMI Compliant PoE Powered Device with Non-Isolated DC/DC	SLUA454
PoE Powered Device for 24 VAC Building Power Applications	SLUA477
Using the TPS2398/99 Hot Swap Controller With Power Trends PT4485	SLUA306

6 Getting Started

6.1 Hardware

The reference design comprises of one board, shown in [Figure 3](#), which has several input capabilities.

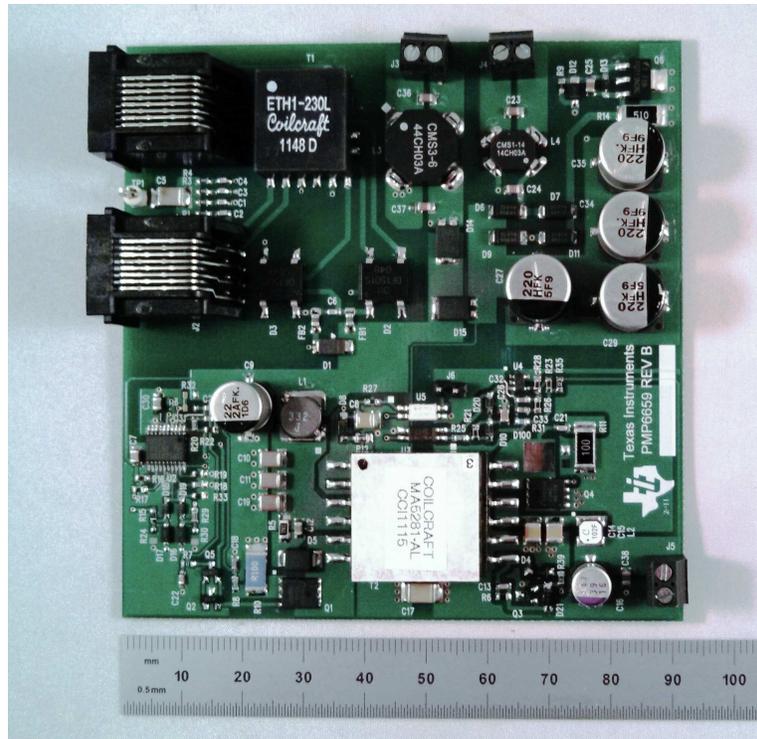


Figure 3. The PMP6659 Board (Revision B)

Figure 4 shows the partition of the PMP6659 board.

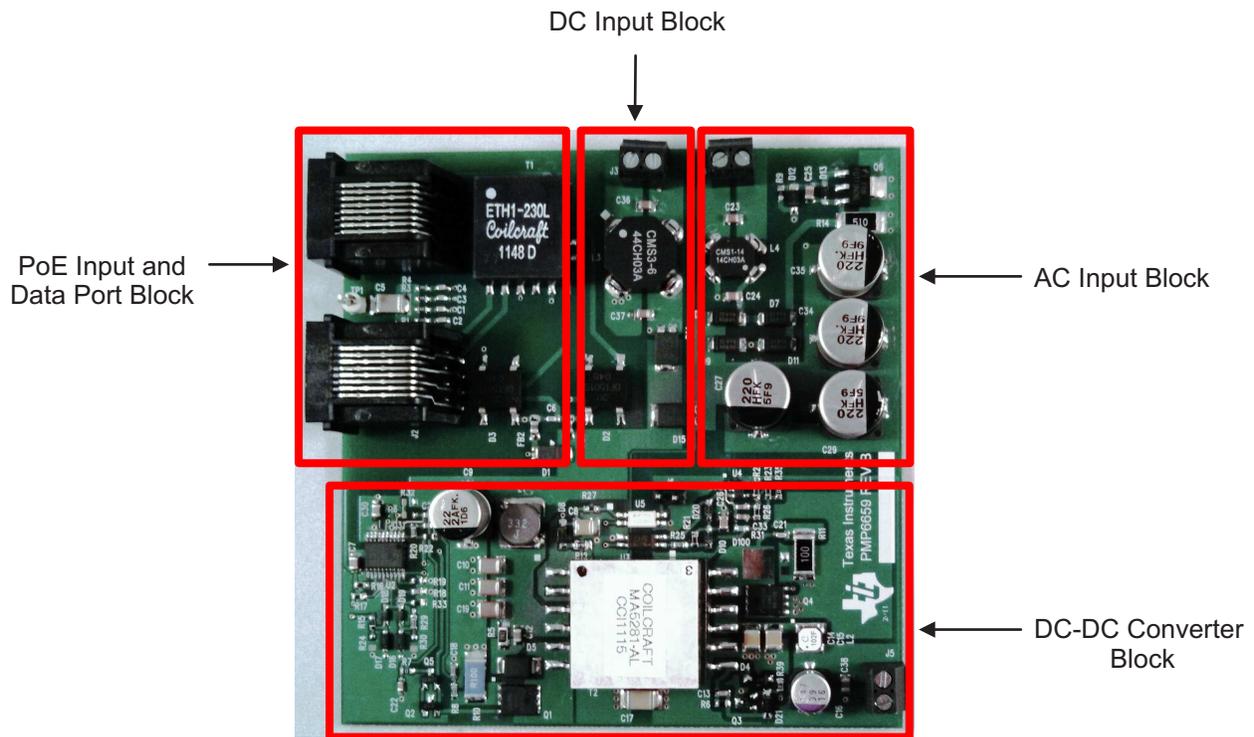


Figure 4. PMP6659 Partition

Figure 5 shows the adapter inputs, PoE input, data port, and the output.

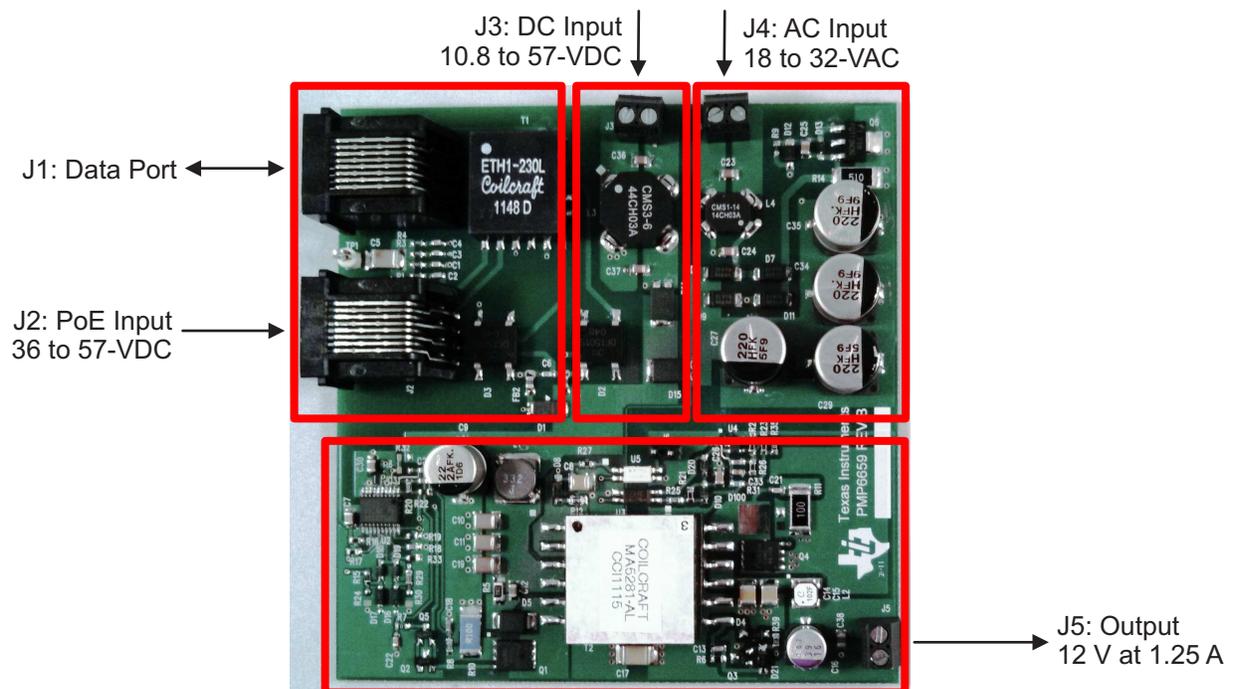


Figure 5. PMP6659 Inputs and Outputs

6.1.1 Hardware Setup

This section lists the different ways to apply power to the PMP6659 board.

6.1.1.1 Connect a DC Adaptor Input

As shown in [Figure 6](#) and [Figure 7](#), connect an adapter input or bench supply of 10.8 to 57 VDC to J3 (see [Section 8](#) for the PMP6659 schematic). The output power is transmitted from the J5 connector.

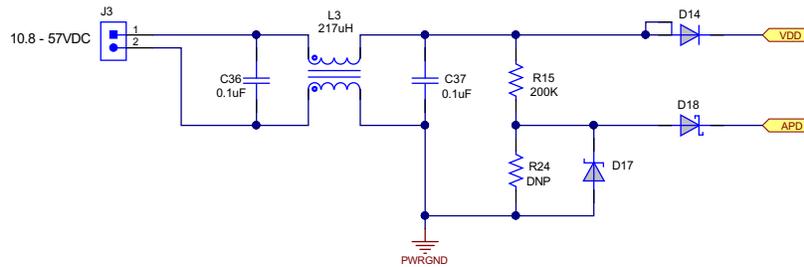


Figure 6. PMP6659 DC-Adaptor Input Schematic

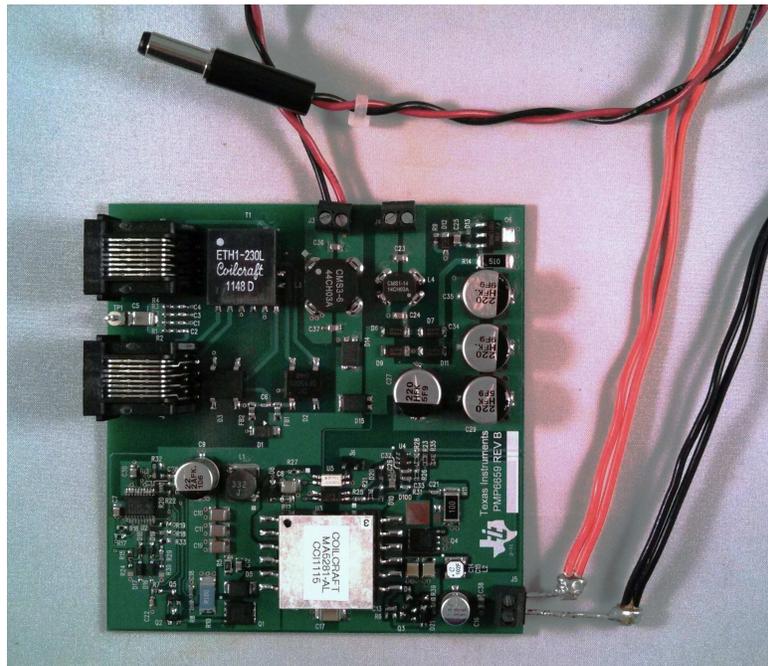


Figure 7. PMP6659 DC-Adaptor Input Setup

6.1.1.2 Connect an AC adapter input

As shown in Figure 8 and Figure 9, connect an adapter input of 18 to 32 VAC to J4 (see Section 8 for the PMP6659 schematic). The output power is transmitted from the J5 connector.

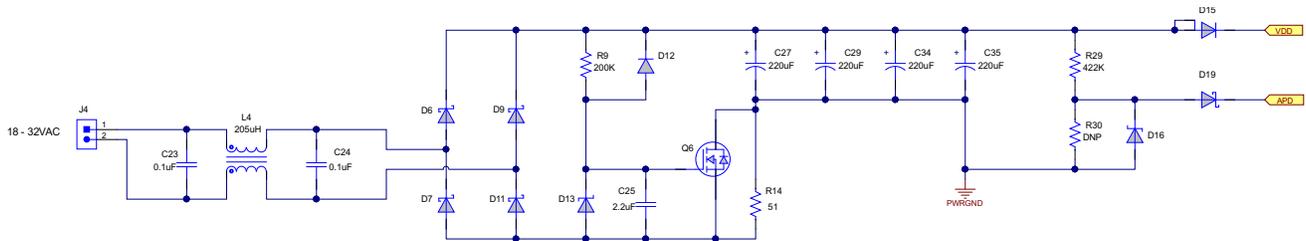


Figure 8. PMP6659 AC-Adapter Input Schematic

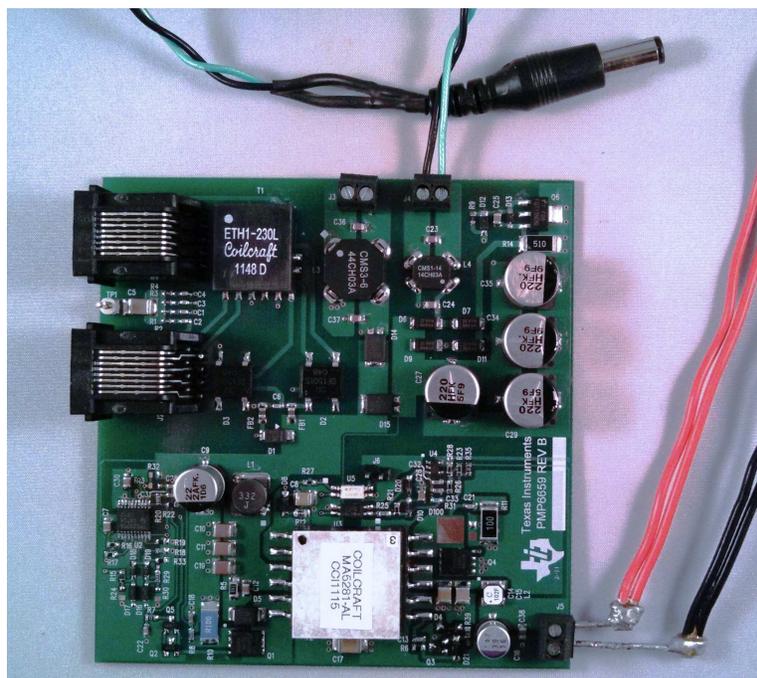


Figure 9. PMP6659 AC-Adapter Input Setup

6.1.1.3 Connect Power over Ethernet

As shown in Figure 10 and Figure 11, connect a Power over Ethernet input or a bench supply to J2 (see Section 8 for the PMP6659 schematic). The output power is transmitted from the J5 connector.

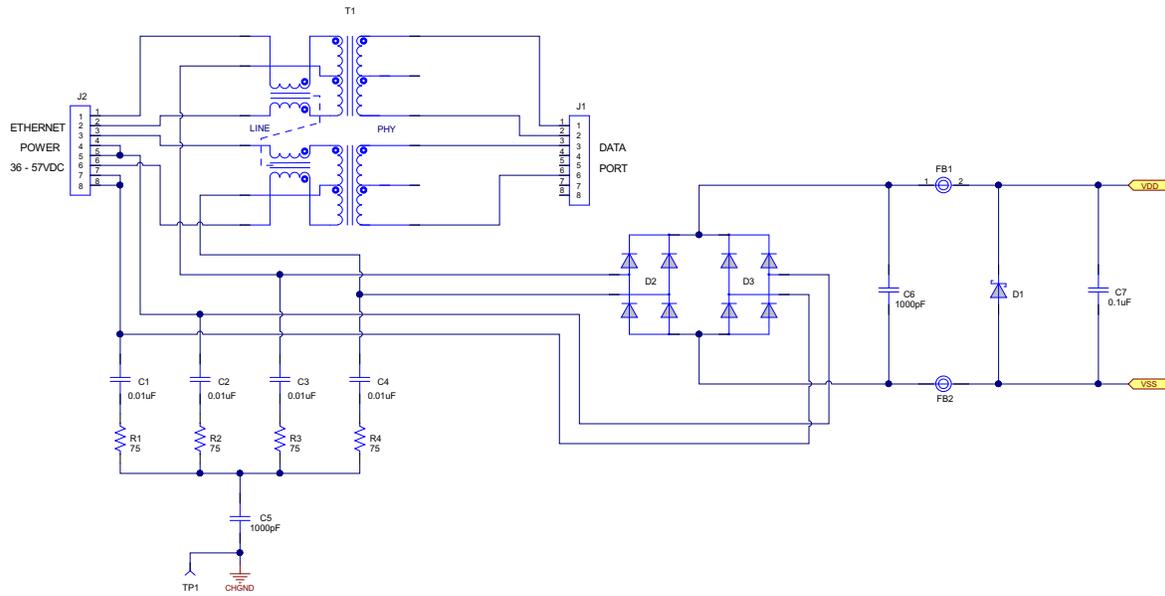


Figure 10. PMP6659 PoE Input Schematic

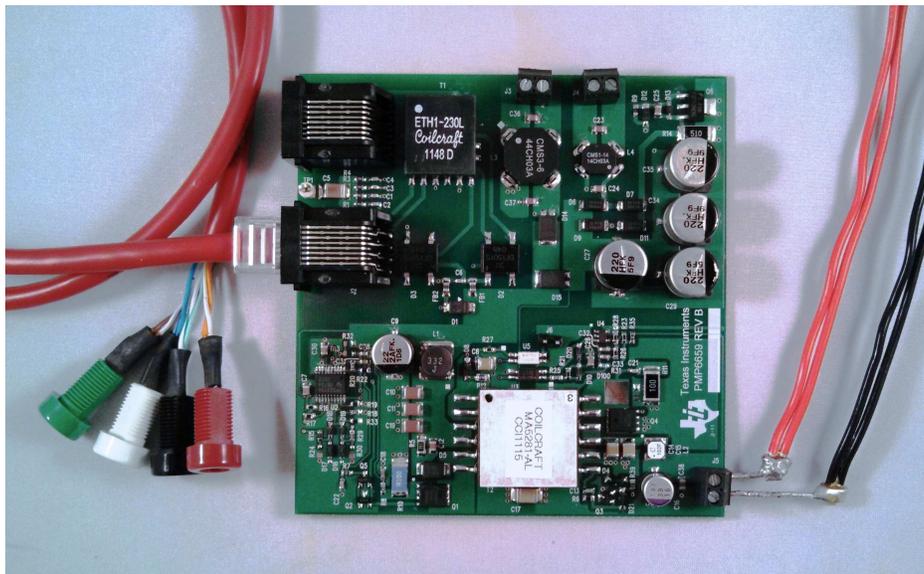


Figure 11. PMP6659 PoE Input Setup

7 Test Data

7.1 Efficiency versus Input Voltage

Figure 12 shows the efficiency of the converter with various inputs. The efficiency data is taken from three points

1. 48-VDC input at J2 (see Figure 10 and Figure 11)
2. 12-VDC input at J3 (see Figure 6 and Figure 7)
3. 24-VAC input at J4 (see Figure 8 and Figure 9)

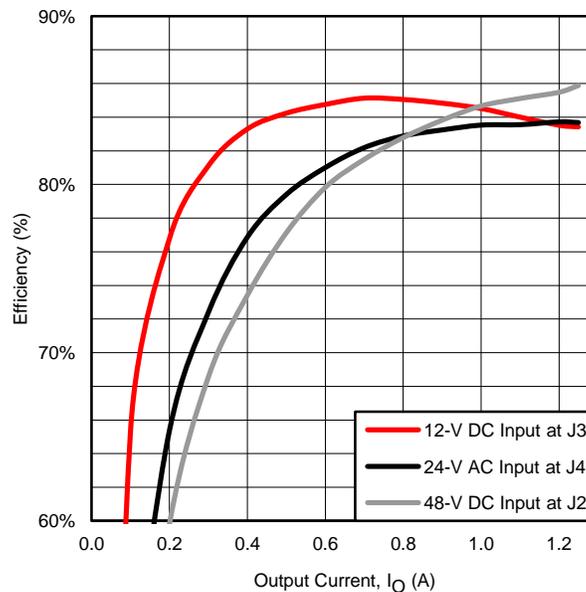


Figure 12. Efficiency of the PMP6659 Across a Wide Input Range

7.2 Input Ripple Voltage (Ripple and Noise Measurements)

Figure 13 and Figure 14 show the ripple voltage (J5 connector). The input ripple shown in Figure 13 and Figure 14 was measured with an input voltage of 48 VDC at J2, an output load at 1.25 A, and 20 MHz BWL.

NOTE: A short ground lead was required for the ripple measurement.

The oscilloscope was set to 20 MHz bandwidth limited.

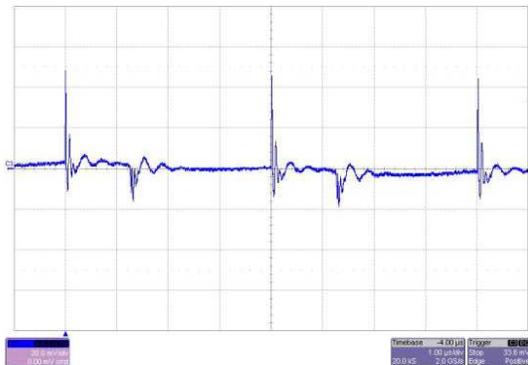


Figure 13. 12-V Ripple (C38), 20 mV/div, 1 μ s/div

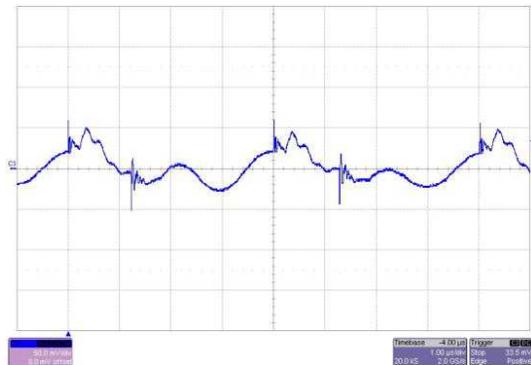


Figure 14. Input Ripple (D1), 10 mV/div, 1 μ s/div

The input ripple shown in Figure 15 and Figure 16 was taken with an input voltage of 12 VDC at J3, the output loaded to 1.25 A, and 20 MHz BWL.



Figure 15. 12-V Ripple (C38), 20 mV/div, 1 μ s/div

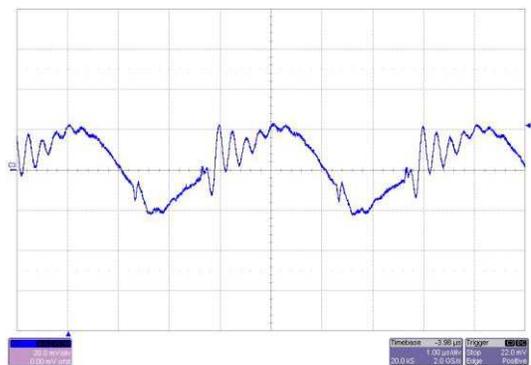


Figure 16. Input Ripple (C37), 10 mV/div, 1 μ s/div

The input ripple shown in [Figure 17](#) was taken with an input voltage of 24 VAC across C27.

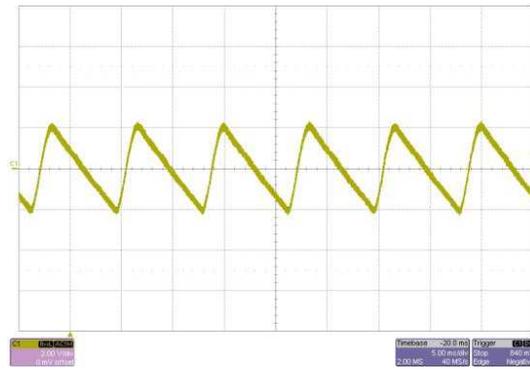


Figure 17. Input Ripple Across C27 with a 24-V AC Input, 2 V/div, 5 ms/div

7.3 Load Transients (Dynamic Loading)

Figure 18 shows the 12-V output voltage (at J5) when the load current pulses between 0.5 A and 1.25 A. The input voltage (V_i) is 48 VDC at J2.

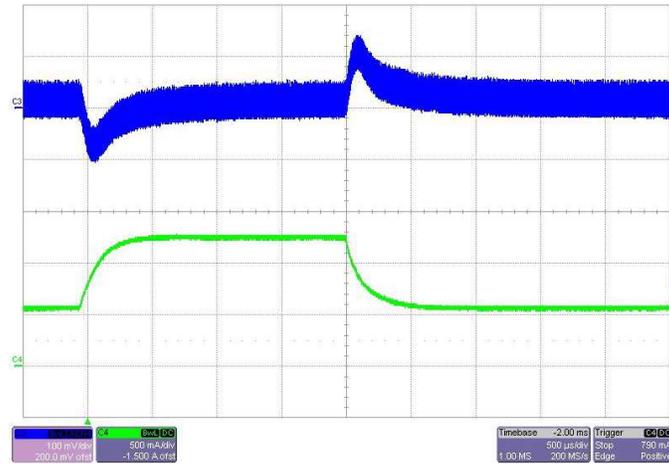


Figure 18. Load Step, 48 V_i at J2 100 mV/div, 500 μ s/div

Figure 19 shows the 12-V output voltage (at J5) when the load current pulses between 0.5 A and 1.25 A. V_i is 12-VDC at J3.

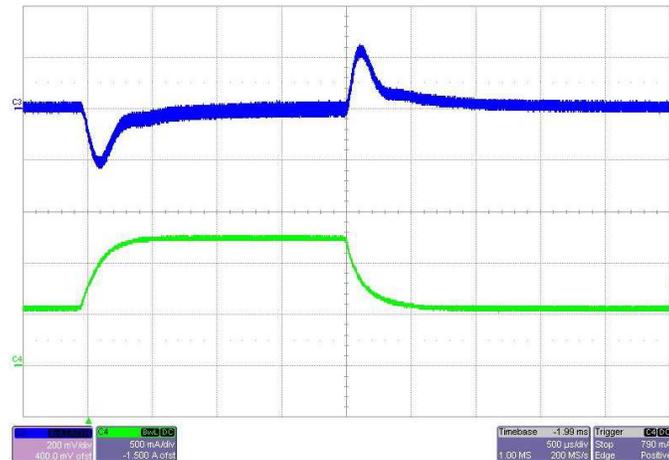


Figure 19. Load Step, 12 V_i at J3 200 mV/div, 1 ms/div

7.4 Turn-on Response

Figure 20 and Figure 21 show the 12-V output voltage start-up waveform after the application of 48 VDC at J2 (PoE). The output was loaded to 0 A (see Figure 20) and 1.25 A (see Figure 21).

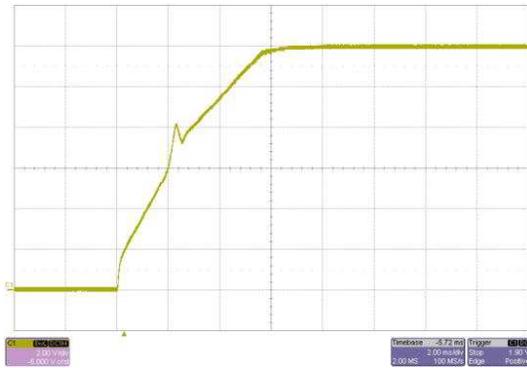


Figure 20. 48 V_I, 0-A Load, 2 ms/div

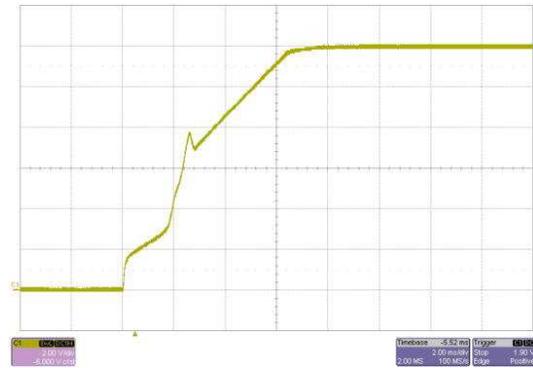


Figure 21. 48 V_I, 1.25-A Load, 2 ms/div

Figure 22 and Figure 23 show the 12-V output voltage start-up waveform after the application of 12 VDC at J3. The output was loaded to 0 A (see Figure 22) and 1.25 A (see Figure 23).

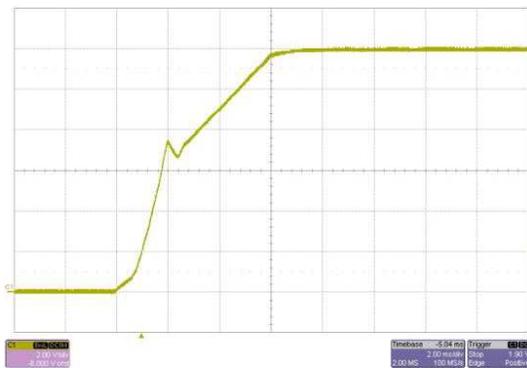


Figure 22. 12 V_I, 0-A Load, 2 ms/div

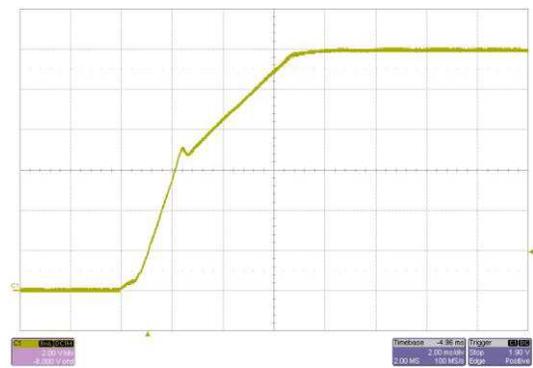


Figure 23. 12 V_I, 1.25-A Load, 2 ms/div

7.5 Control Loop Gain / Stability

Table 2 lists the loop gain and phase margin (see Figure 24). The output was loaded to 1.25 A.

Table 2. Loop Gain and Phase Margin at 48 V

Input Voltage	48-V	
Gain/Phase	Crossover	Phase Margin
PMP6659	6.4 kHz	58.3°

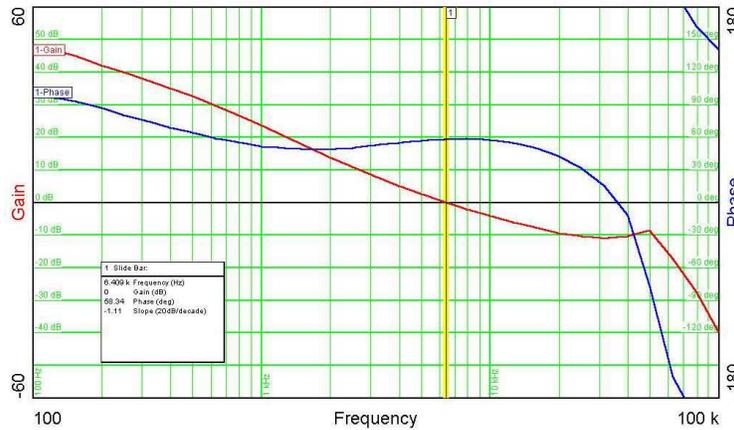


Figure 24. Loop Gain and Phase Margin at 48 V

Table 3 lists the loop gain and phase margin (see Figure 25). The output was loaded to 1.25 A.

Table 3. Loop Gain and Phase Margin at 12 V

Input Voltage	12-V	
Gain/Phase	Crossover	Phase Margin
PMP6659	3.3 kHz	36°

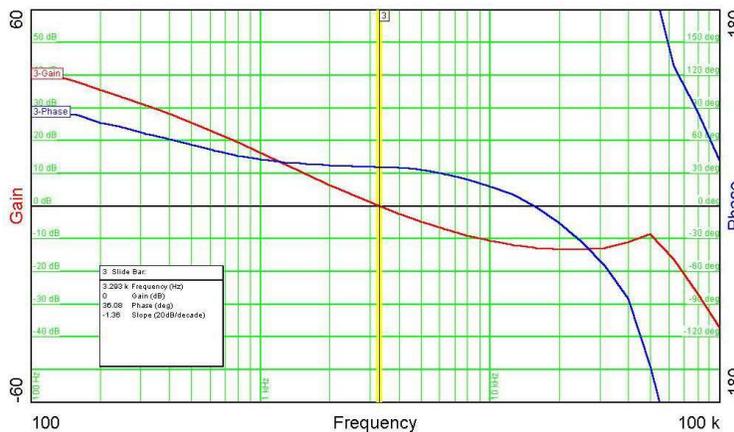


Figure 25. Loop Gain and Phase Margin at 12 V

7.6 Thermal Performance of the Design

A simple test confirmed the thermal performance of the design. Thermal measurements were taken at two data points: 48-V input with a 1.25-A load and 12-V input with a 1.25-A load.

Thermal-imaging camera hot spots were analyzed at 30 minutes after launching the application. The results of this test confirm that the design can effectively dissipate heat without localized heating.

As shown in [Figure 26](#) and [Figure 27](#), there is no localized heating observed in the system after the 30 minute period.

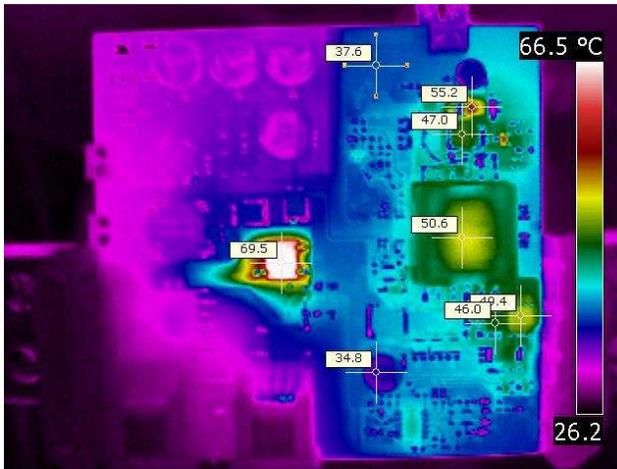


Figure 26. 48-V Input and 1.25-A Load



Figure 27. 12-V Input and 1.25-A Load

8 Schematics

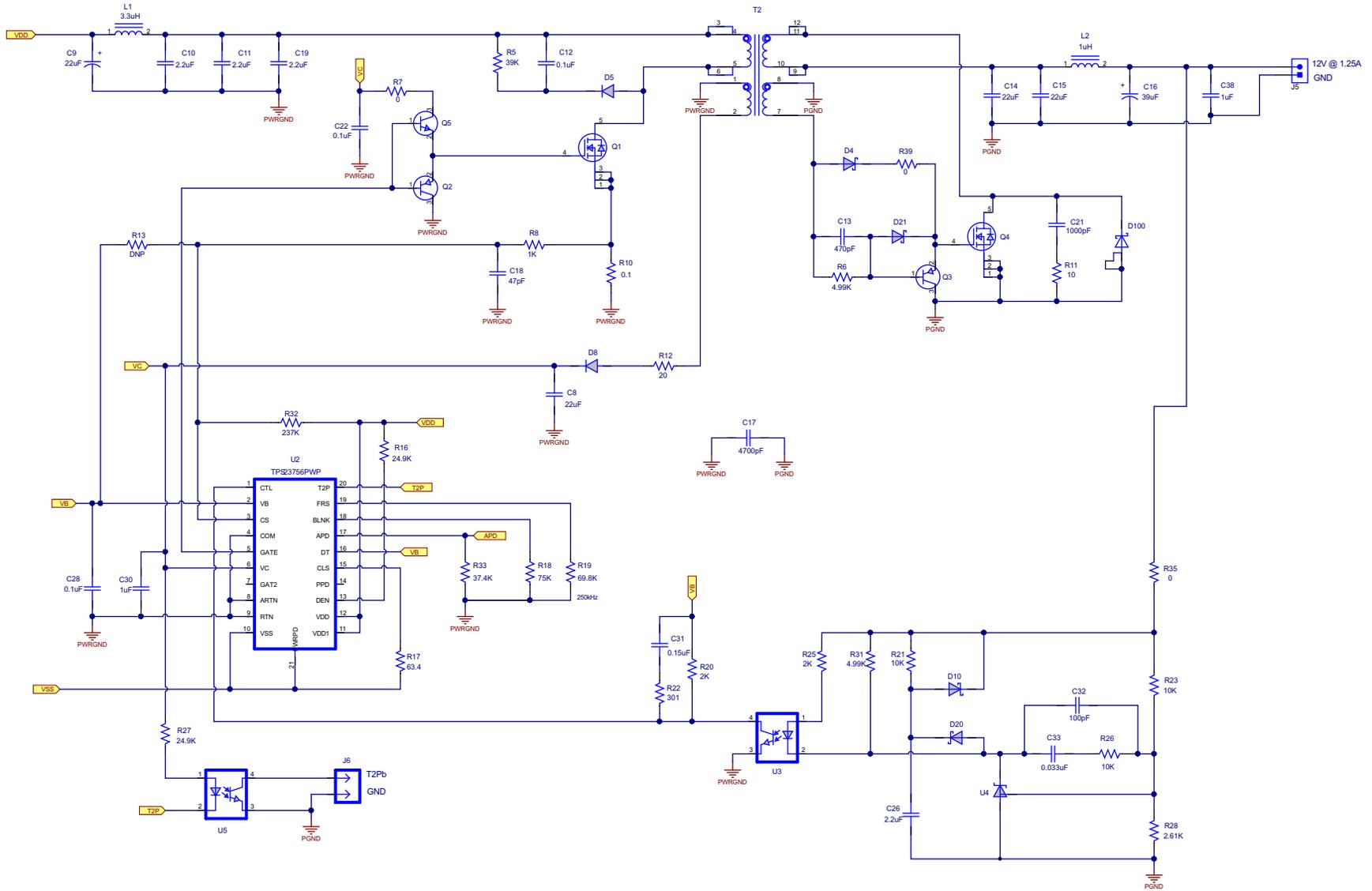


Figure 28. The DC-DC Converter

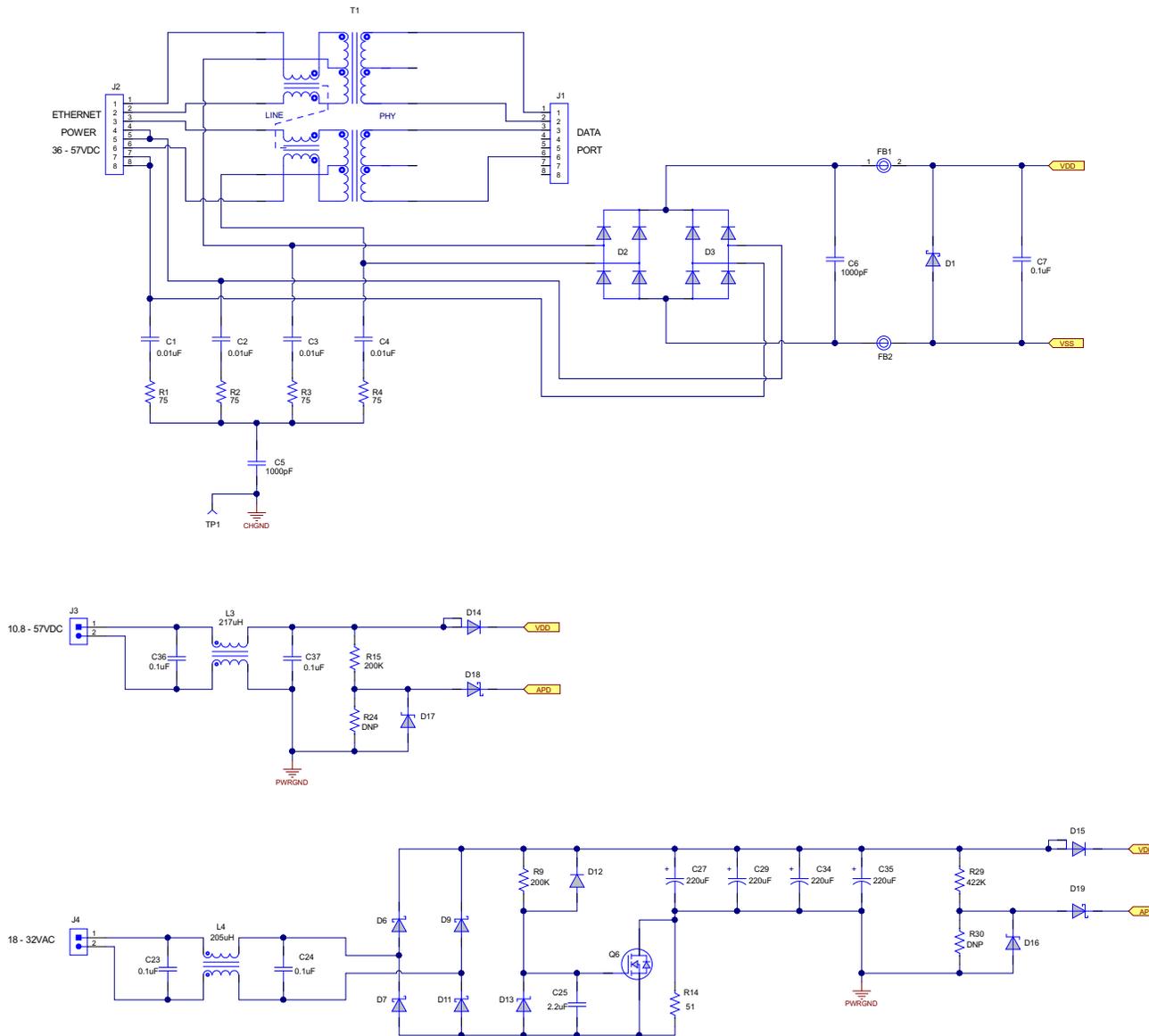


Figure 29. The Adapter Inputs, PoE Input, and Data Port

9 Bill of Materials

To download the bill of materials (BOM) for each board, see the design files at www.ti.com/tool/PMP6659. Table 4 lists the BOM for the PMP6659.

Table 4. BOM

Designator	Quantity	Value	Description	Package Reference	Part Number	Manufacturer
!PCB	1		Printed Circuit Board		PMP6659	Any
C1, C2, C3, C4	4	0.01 μ F	Capacitor, Ceramic, 100 V, X7R, 10%	603	STD	STD
C5	1	1000 pF	Capacitor, Ceramic, 2 KV, X7R, 10%	1812	Std	Std
C6, C21	2	1000 pF	Capacitor, Ceramic, 100 V, C0G, 10%	603	STD	STD
C7, C12, C23, C24, C36, C37	6	0.01 μ F	Capacitor, Ceramic, 100 V, X7R, 10%	805	STD	STD
C8, C14, C15	3	22 μ F	Capacitor, Ceramic, 25 V, X7R, 10%	1210	Std	STD
C9	1	22 μ F	Capacitor, Aluminum Electrolytic, 100 V, 20%	0.328 x 0.390 inch	EEVFKxyyyF	Panasonic
C10, C11, C19	3	2.2 μ F	Capacitor, Ceramic, 100 V, X7R, 10%	1210	Std	STD
C13	1	470 pF	Capacitor, Ceramic, 16 V, X7R, 10%	603	STD	STD
C16	1	39 μ F	Capacitor, OS CON, 16 V, 50 m Ω , 20%	0.260 inch ²	vvSVPxxxM	Sanyo
C17	1	4700 pF	Capacitor, Ceramic, 2 KV, X7R, 10%	1812	Std	Std
C18	1	47 pF	Capacitor, Ceramic, 50 V, C0G, 10%	603	STD	STD
C22, C28	2	0.01 μ F	Capacitor, Ceramic, 25V, X7R, 10%	603	STD	STD
C25, C26	2	2.2 μ F	Capacitor, Ceramic, 16V, X7R, 10%	805	STD	STD
C27, C29, C34, C35	4	220 μ F	Capacitor, Aluminum Electrolytic, 50V, 20%	0.457 x 0.406	EEVFKxyyyP	Panasonic
C30, C38	2	1 μ F	Capacitor, Ceramic, 25V, X7R, 10%	805	STD	STD
C31	1	0.15 μ F	Capacitor, Ceramic, 16V, X7R, 10%	603	STD	STD
C32	1	100 pF	Capacitor, Ceramic, 25V, C0G, 10%	603	STD	STD
C33	1	0.033 μ F	Capacitor, Ceramic, 25V, X7R, 10%	603	STD	STD
D1	1	SMAJ58A	Diode, SMT TVS 400W, 4.3-A, 58-V	SMA	SMAJxxxCA	Diodes
D2, D3	2	DF1501S	Bridge Rectifier, 100 V, 1.5 A, Glass Passivated, SMD	DF-S	DFXXXS	Diodes
D4, D21	2	MBR0530	Diode, Schottky, 0.5 A, 30 V	SOD-123	MBR0520L	Fairchild
D5	1	ES3CB	Diode, Rectifier, Ultra-fast, 3 A, 150 V	SMB	STD	STD
D6, D7, D9, D11	4	B260A	Diode, Schottky, 2 A, 60 V	SMA	STD	STD
D8, D12	2	MMSD4148	Diode, Switching, 100 V, 200 mA, 400 mW,	SOD-123	MMSD4148	On Semi
D10, D18, D19, D20	4	BAT54HT1	Diode, Schottky, 200 mA, 30 V, 200 mW	SOD323	BAT54HT1	On Semi
D13	1	10 V	Diode, Zener, 200 mW, 10 V	SOD-323	BZT52CxxxS	Conitnental Devices India Limited
D14, D15	2	PDU620	Diode, 6 A 200 V Ultra-Fast Recovery	PowerDI 5	PDU620	Diodes
D16, D17	2	5.1 V	Diode, Zener, 200 mW, 5.1 V	SOD-323	BZT52CxxxS	Conitnental Devices India Limited
D100	1	DNP	Diode, High Current,Trench MOS Barrier Schottky, 100V, 8A			
FB1, FB2	2	MMZ2102R150A	Bead, Ferrite, 1.5 A, 15 Ω	0805	MI0805KxxxR-00	Steward
FID1, FID2, FID3	3		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A
J1, J2	2	520252	Connector, Jack, Modular, 8 POS			
J3, J4, J5	3		Terminal Block, 6 A, 3.5-mm Pitch, 2-Pos, TH	7,0 x 8,2 x 6,5 mm	ED555/2DS	On-Shore Technology
J6	1	PTC36SAAN	Header, Male 2-pin, 100 mil spacing, (36-pin strip)	0.100 inch x 2	PEC02SAAN	Sullins
L1	1	3.3 μ H	Inductor, SMT, 3.95 A, 20 m Ω	0.287 x 0.287 inch	MSS7341-xxxML	Coilcraft

Table 4. BOM (continued)

Designator	Quantity	Value	Description	Package Reference	Part Number	Manufacturer
L2	1	1 μ H	Inductor, SMT, 1.8 A, 42 m Ω	0.153 x 0.153 inch	LPS4018-xxxxX	Coilcraft
L3	1	217 μ H	Inductor, Common Mode, 2.85 A, 20 m Ω	0.550 x 0.550 inch	CMS-3 EMI	Cooper
L4	1	205 μ H	Inductor, Common Mode, 850 mA, 186 m Ω	0.370 x 0.283 inch	CMS1-xx	Cooper
Q1	1	FDMS86200	MOSFET, NChan, 150 V, 9.6 A, 18 m Ω	POWER 56	FDMS8690	Fairchild
Q2, Q3	2	MMBT3906	Trans, PNP, 40 V, 200 mA, 225 mW	SOT23	MMBT3906LT1G	On Semi
Q4	1	FDMS86105	MOSFET, NChan, 100V, 6A, 34 m Ω	POWER 56	FDMS8690	Fairchild
Q5	1	MMBT3904	Trans, NPN, 40 V, 200 mA, 225 mW	SOT23	MMBT3904LT1G	On Semi
Q6	1	FQT13N06L	MOSFET, N-ch, 60 V, 2.8 A , 0.11 Ω	SOT223-4	FQT13N06L	Fairchild
R1, R2, R3, R4	4	75	Resistor, Chip, 1/16W, 1%	603	STD	STD
R5	1	39K	Resistor, Chip, 1/4W, 5%	1206	Std	Std
R6, R31	2	4.99K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R7, R35, R39	3	0	Resistor, Chip, 1/16W, 1%	603	STD	STD
R8	1	1K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R9, R15	2	200K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R10	1	0.1	Resistor, Chip, 1W, 5%	2512	STD	STD
R11	1	10	Resistor, Chip, 1W, 5%	2512	STD	STD
R12	1	20	Resistor, Chip, 1/10W, 5%	805	STD	STD
R13, R24, R30	3	DNP	Resistor, Chip, 1/16W, 1%	603	STD	STD
R14	1	51	Resistor, Chip, 1W, 5%	2512	STD	STD
R16, R27	2	24.9K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R17	1	63.4	Resistor, Chip, 1/16W, 1%	603	STD	STD
R18	1	75K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R19	1	69.8K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R20, R25	2	2K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R21, R23, R26	3	10K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R22	1	301	Resistor, Chip, 1/16W, 1%	603	STD	STD
R28	1	2.61K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R29	1	422K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R32	1	237K	Resistor, Chip, 1/16W, 1%	603	STD	STD
R33	1	37.4K	Resistor, Chip, 1/16W, 1%	603	STD	STD
T1	1	ETH1-230LD	Transformer, High Power PoE	S0 14 Wide	ETH1-230LD	Coilcraft
T2	1	MA5281-BL	Transformer, Flyback, 45uH	0.810 x 1.181 inch	MA5281-AL	Coilcraft
TP1	1	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
U2	1	TPS23756PWP	IC, IEEE 802.3at PoE Interface/Isolated Converter Controller	PWP20	TPS23754PWP	TI
U3	1	TCMT1107	IC, Photocoupler, 80-160% CTR	MF4	TCMT110x	Vishay
U4	1	TL431ACDBVR	IC, Precision Adjustable Shunt Regulator	SOT23-5	TL431DBVR	TI
U5	1	TCMT1109	IC, Photocoupler, 200-400% CTR	MF4	TCMT110x	Vishay

10 Layer Plots

To download the layer plots for each board, see the design files at www.ti.com/tool/PMP6659. Figure 30 shows the layer plots.

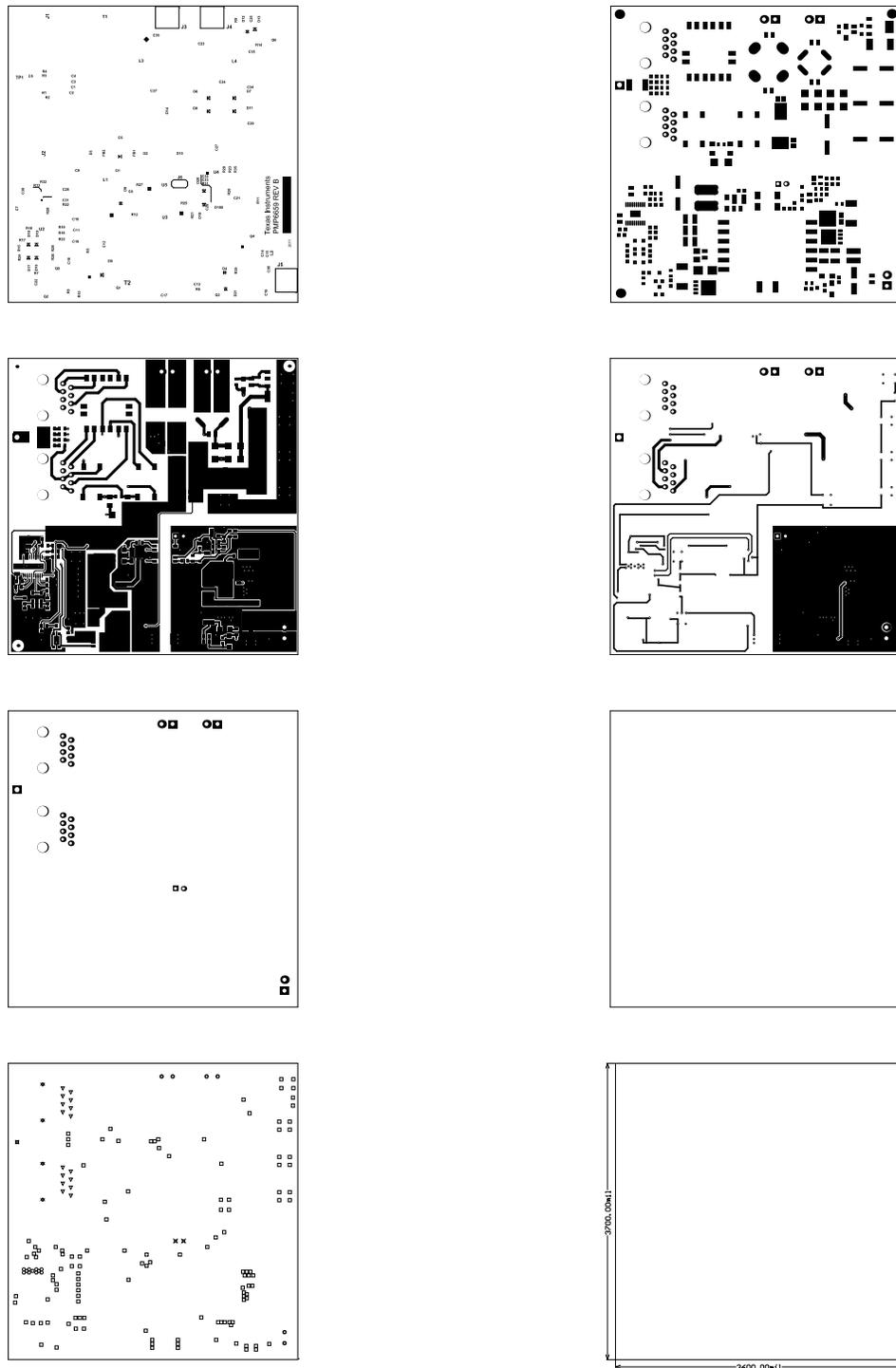


Figure 30. PMP6659 Layer Plot

11 Assembly Drawings

To download the assembly drawings, see the design files at www.ti.com/tool/PMP6659. Figure 31 shows the assembly drawing for the PMP6659 board.

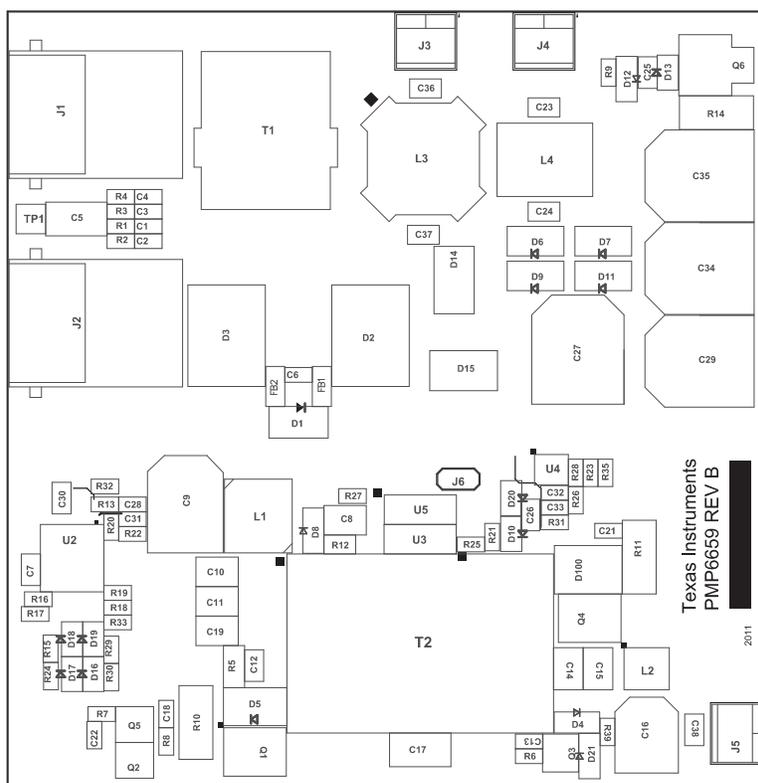


Figure 31. PMP6659 Assembly Drawing

12 Altium Project

To download the Altium project files, see the design files at www.ti.com/tool/PMP6659. Figure 32 shows the layout for the PMP6659.

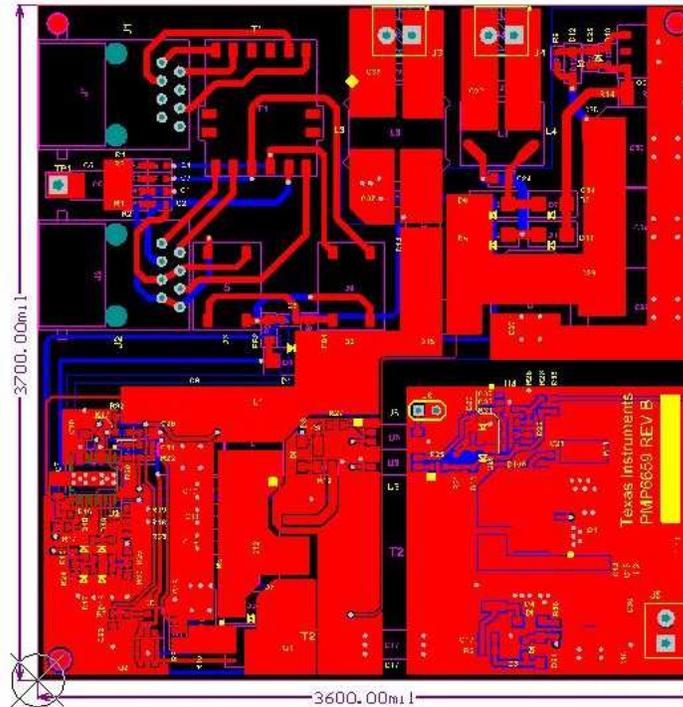


Figure 32. PMP6659 Layout

13 Gerber Files

To download the Gerber files for each board, see the design files at www.ti.com/tool/PMP6659

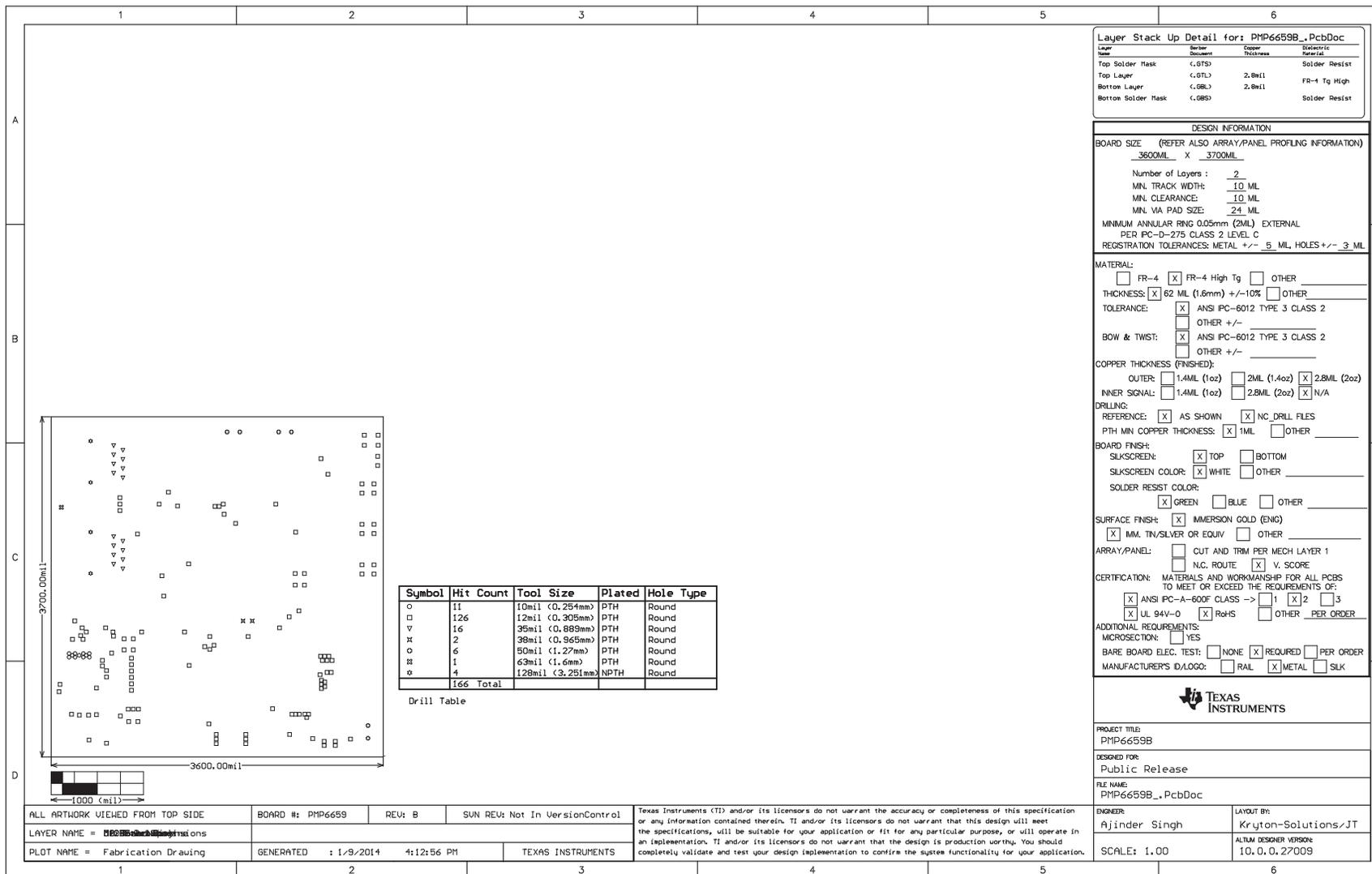


Figure 33. PMP6659 Fab Drawings

14 About the Author

David Strasser is a Senior Applications Engineer and Member Group Technical Staff at Texas Instruments where he is responsible for developing power reference designs across a wide array of markets. David brings to this role over 30 years of experience in power conversion design. David earned his Bachelor of Science in Electrical Engineering from Western Michigan University in Kalamazoo, Michigan and his Master of Science in Electrical Engineering from the Illinois Institute of Technology in Chicago, Illinois.

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For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC – INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

【Important Notice for Users of EVMs for RF Products in Japan】

This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

1. Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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